Product Change Notification - SYST-20CSDX683

Date:

26 Jul 2019

Product Category:

Clock and Timing - Clock and Data Distribution

Affected CPNs:

Notification subject:

Data Sheet - SY58607U Data Sheet

Notification text:

SYST-20CSDX683

Microchip has released a new DeviceDoc for the SY58607U Data Sheet of devices. If you are using one of these devices please read the document located at SY58607U Data Sheet.

Notification Status: Final

Description of Change: 1) Converted Micrel document SY58607U to Microchip data sheet template DS20006227A. 2) Minor text changes throughout.

Impacts to Data Sheet: None

Reason for Change: To Improve Manufacturability

Change Implementation Status: Complete

Date Document Changes Effective: 26 July 2019

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachment(s):

SY58607U Data Sheet

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

SY58607U

3.2 Gbps Precision, 1:2 LVPECL Fanout Buffer with Internal Termination and Fail Safe Input

Features

- Precision 1:2, 800 mV LVPECL Fanout Buffer
- Guaranteed AC Performance over Temperature and Voltage:
  - DC-to >3.2 Gbps Throughput
  - <350 ps Propagation Delay (IN-to-Q)
  - <20 ps Within-Device Skew
  - <110 ps Rise/Fall Times
- Fail Safe Input
  - Prevents Outputs From Oscillating When Input is Invalid
- Ultra-Low Jitter Design
  - 41 fs Additive Phase Jitter
- High-Speed LVPECL Outputs
- 2.5V ±5% or 3.3V ±10% Power Supply Operation
- Industrial Temperature Range: –40°C to +85°C
- Available in 16-lead (3 mm x 3 mm) QFN Package

Applications

- All SONET Clock and Data Distribution
- Fibre Channel Clock and Data Distribution
- Gigabit Ethernet Clock And Data Distribution
- Backplane Distribution

Markets

- Storage
- ATE
- Test and Measurement
- Enterprise Networking Equipment
- High-End Servers
- Access
- Metro Area Network Equipment

General Description

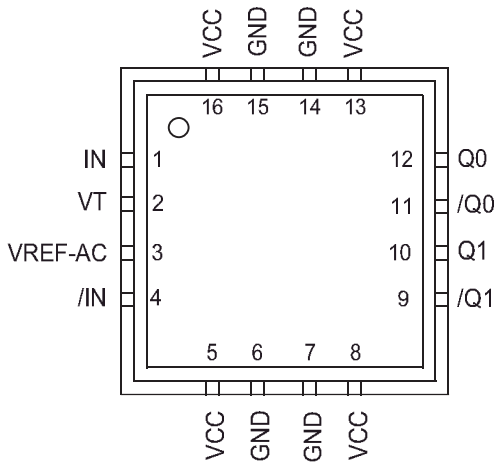
The SY58607U is a 2.5V/3.3V, high-speed, fully differential 1:2 LVPECL fanout buffer optimized to provide two identical output copies with less than 20 ps of skew. The SY58607U can process clock signals as fast as 2.5 GHz or data patterns up to 3.2 Gbps.

The differential input includes Microchip's unique, 3-lead input termination architecture that interfaces to LVPECL, LVDS, or CML differential signals, (AC- or DC-coupled) as small as 100 mV (200 mV_{PP}) without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an integrated voltage reference (VREF-AC) is provided to bias the VT pin. The outputs are 800 mV LVPECL, with extremely fast rise/fall times guaranteed to be less than 110 ps.

The SY58607U operates from a 2.5V ±5% supply or 3.3V ±10% supply and is guaranteed over the full industrial temperature range (–40°C to +85°C). For applications that require CML or LVDS outputs, consider Microchip's SY58606U and SY58608U, 1:2 fanout buffers with 400 mV and 325 mV output swings respectively. The SY58607U is part of Microchip's high-speed, Precision Edge® product line.

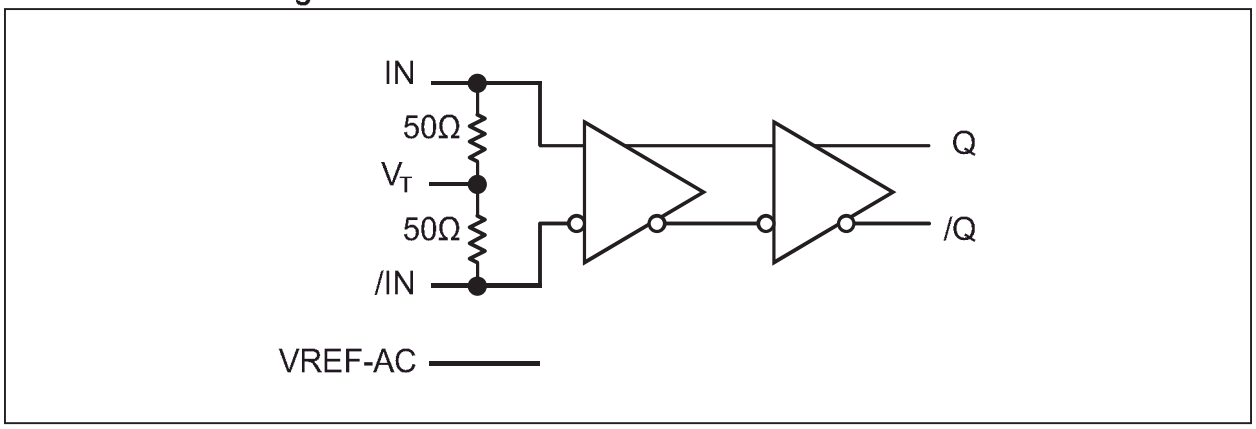
Package Type

SY58607U
3 mm x 3 mm QFN-16 (M)
(Top View)



United States Patent No. RE44,134

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage (V_{CC}) ..... –0.5V to +4.0V
Input Voltage (V_{IN}) ..... –0.5V to V_{CC}
LVPECL Output Current (I_{OUT})
    Continuous ..... 50 mA
    Surge ..... 100 mA
Current (I_{VT})
    Source or Sink on VT Pin ..... ±100 mA
Input Current
    Source or Sink Current on IN, /IN ..... ±50 mA
Current (I_{REF})
    Source or Sink Current on VREF-AC (Note 1) ..... ±1.5 mA

Operating Ratings ††

Supply Voltage (V_{CC}) ..... +2.375V to +3.60V

† Notice: Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

†† Notice: The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

Note 1: Due to the limited drive capability, use for input of the same package only.

DC ELECTRICAL CHARACTERISTICS (Note 1)

Electrical Characteristics: T_A = –40°C to +85°C, unless otherwise stated.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Power Supply Voltage Range	V_{CC}	2.375	2.5	2.625	V	—
		3.0	3.3	3.6		
Power Supply Current	I_{CC}	—	40	60	mA	No load, max. V_{CC}
Differential Input Resistance (IN-to-/IN)	R_{DIFF_IN}	90	100	110	Ω	—
Input HIGH Voltage (IN, /IN)	V_{IH}	V_{CC} – 1.6	—	V_{CC}	V	IN, /IN, Note 2
Input LOW Voltage (IN, /IN)	V_{IL}	0	—	V_{IH} – 0.1	V	IN, /IN
Input Voltage Swing (IN, /IN)	V_{IN}	0.1	—	1.7	V	See Figure 5-5, Note 3
Differential Input Voltage Swing (|IN - /IN|)	V_{DIFF_IN}	0.2	—	—	V	See Figure 5-6
Input Voltage Threshold that Triggers FSI	V_{IN_FSI}	—	30	100	mV	—
Output Reference Voltage	V_{REF-AC}	V_{CC} – 1.3	V_{CC} – 1.2	V_{CC} – 1.1	V	—
Voltage from Input to VT	V_{T_IN}	—	—	1.28	V	—

Note 1: The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

2: $V_{IH(MIN)}$ not lower than 1.2V.

3: $V_{IN(MAX)}$ is specified when VT is floating.

LVPECL OUTPUTS DC ELECTRICAL CHARACTERISTICS (Note 1)

Electrical Characteristics: V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 50Ω to V_{CC} – 2V; T_A = –40°C to +85°C, unless otherwise stated.

Parameter	Symbol	Min.	Typ.	Max.	Units	Condition
Output High Voltage	V_{OH}	V_{CC} – 1.145	—	V_{CC} – 0.895	V	—
Output Low Voltage	V_{OL}	V_{CC} – 1.945	—	V_{CC} – 1.695	V	—
Output Voltage Swing	V_{OUT}	550	800	950	mV	See Figure 5-5
Differential Output Voltage Swing	V_{DIFF_OUT}	1100	1600	—	mV	See Figure 5-6

Note 1: The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC ELECTRICAL CHARACTERISTICS

Electrical Characteristics: V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 50Ω to V_{CC} – 2V; Input t_r/t_f: ≤300 ps; T_A = –40°C to +85°C, unless otherwise stated.

Parameter	Symbol	Min.	Typ.	Max.	Units	Condition
Maximum Frequency	f_{MAX}	3.2	4.25	—	Gbps	NRZ (Data)
		2.5	3.0	—	GHz	V_{OUT} > 400 mV (Clock)
Propagation Delay IN-to-Q	t_{PD}	180	300	450	ps	V_{IN}: 100 mV - 200 mV
		150	230	350	ps	V_{IN}: 200 mV - 800 mV
Within Device Skew	t_{SKEW}	—	4	20	ps	Note 1
Part-to-Part Skew		—	—	135	ps	Note 2
RMS Phase Jitter	t_{JITTER}	—	47	—	fs	622 MHz Integration Range: 12 kHz to 20 MHz
		—	159	—		156.25 MHz Integration Range: 12 kHz to 20 MHz
		—	290	—		100 MHz Integration Range: 12 kHz to 20 MHz
Additive Phase Jitter		—	41	—	fs	622 MHz Integration Range: 12 kHz to 20 MHz
		—	152	—		156.25 MHz Integration Range: 12 kHz to 20 MHz
		—	282	—		100 MHz Integration Range: 12 kHz to 20 MHz
Output Rise/Fall Time (20% to 80%)	t_r, t_f	40	75	110	ps	At full output swing
Duty Cycle	—	47	—	53	%	Differential I/O

Note 1: Within-Device skew is measured between two different outputs under identical input transitions.

2: Part-to-Part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Operating Ambient Temperature Range	T_A	–40	—	+85	°C	—
Maximum Operating Junction Temperature	T_J	—	—	+125	°C	—
Lead Temperature	—	—	—	+260	°C	Soldering, 20 sec.
Storage Temperature Range	T_S	–65	—	+150	°C	—
Package Thermal Resistances (Note 1)						
Thermal Resistance, 3x3 QFN-16Ld	θ_{JA}	—	60	—	°C/W	Still-air
	Ψ_{JB}	—	33	—	°C/W	Junction-to-board

Note 1: Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. Ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

V_{CC} = 3.3V, GND = 0V, R_L = 50Ω to V_{CC} – 2V, T_A = +25°C, unless otherwise stated.

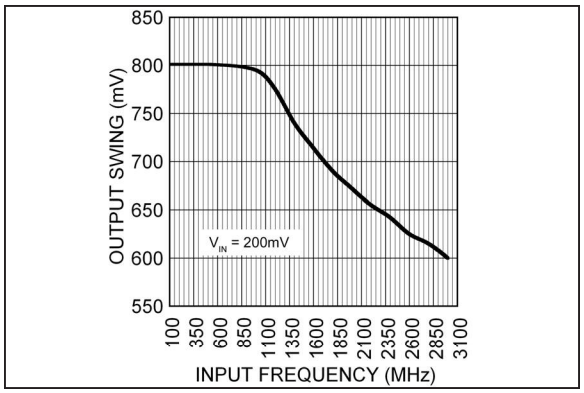


FIGURE 2-1: *Frequency Response.*

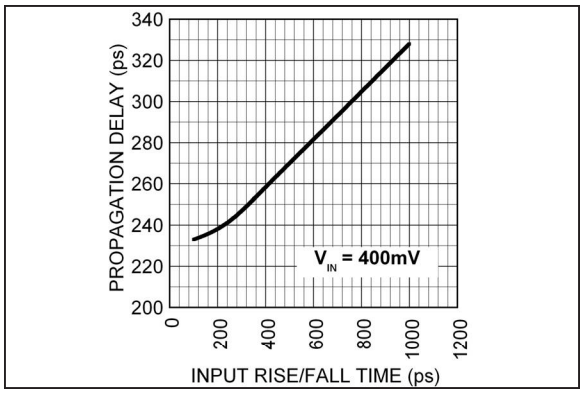


FIGURE 2-4: *Propagation Delay vs. Input Rise/Fall Time.*

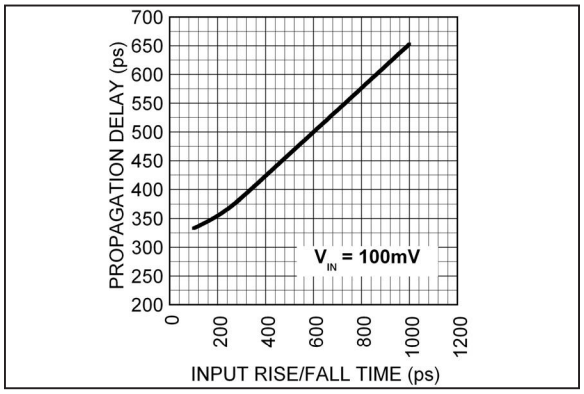


FIGURE 2-2: *Propagation Delay vs. Input Rise/Fall Time.*

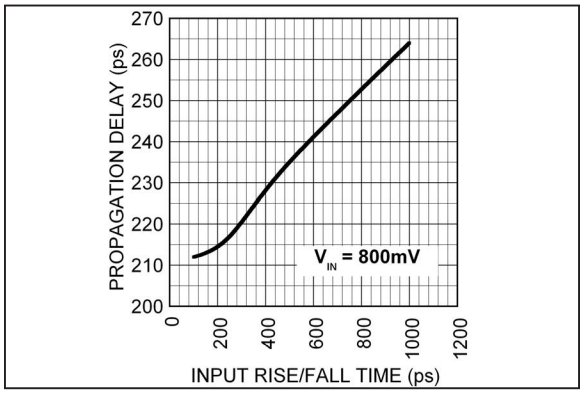


FIGURE 2-5: *Propagation Delay vs. Input Rise/Fall Time.*

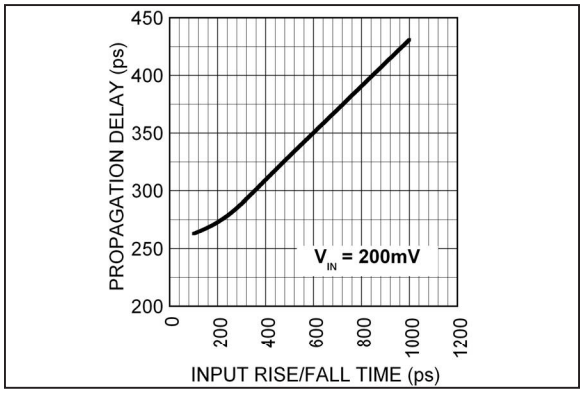


FIGURE 2-3: *Propagation Delay vs. Input Rise/Fall Time.*

V_{CC} = 3.3V, GND = 0V, V_{IN} = 400 mV, Data Pattern: 2^{23}-1, R_L = 50Ω to V_{CC} – 2V, T_A = +25°C, unless otherwise stated.

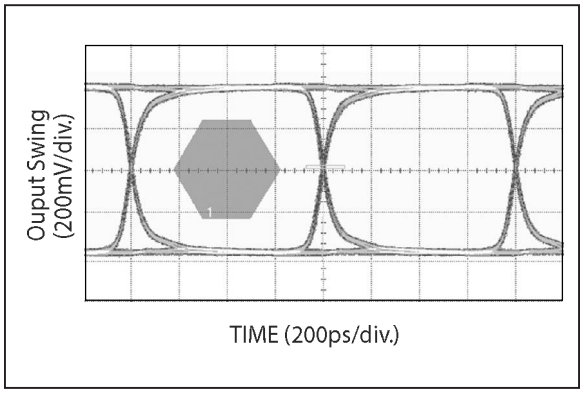


FIGURE 2-6: *1.25 Gbps Data.*

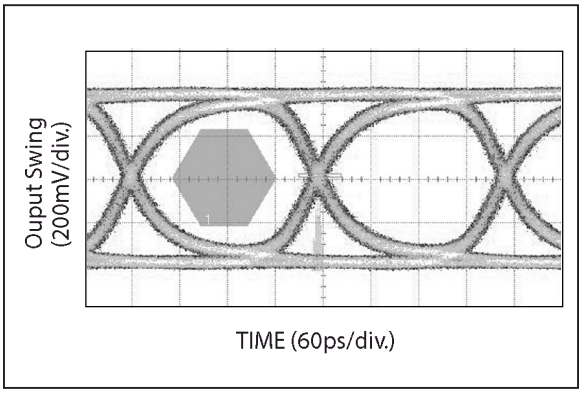


FIGURE 2-9: *4.25 Gbps Data.*

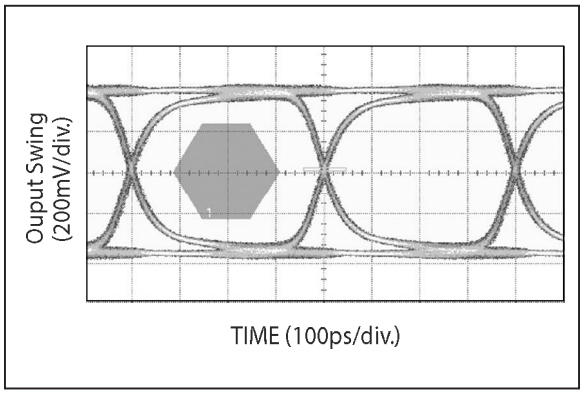


FIGURE 2-7: *2.5 Gbps Data.*

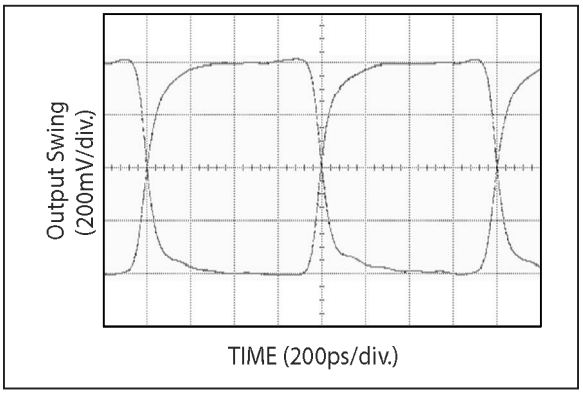


FIGURE 2-10: *625 MHz Clock.*

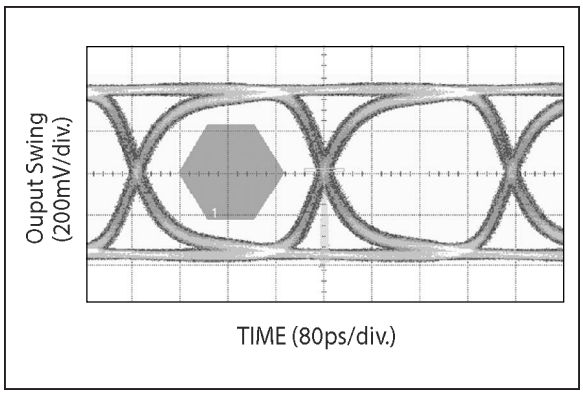


FIGURE 2-8: *3.2 Gbps Data.*

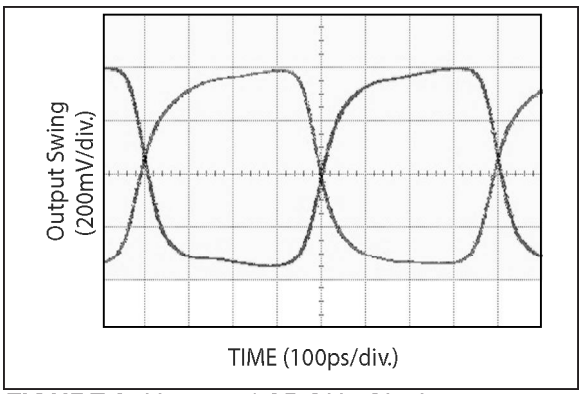


FIGURE 2-11: *1.25 GHz Clock.*

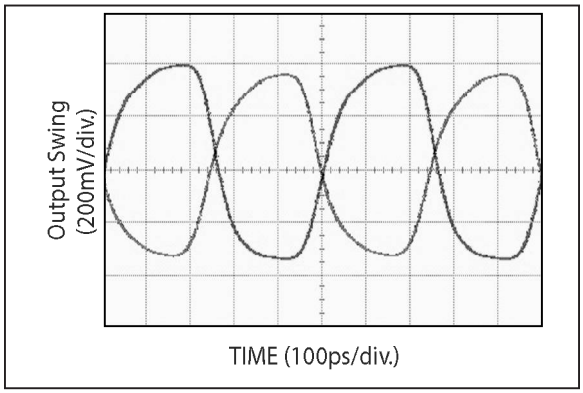


FIGURE 2-12: *2 GHz Clock.*

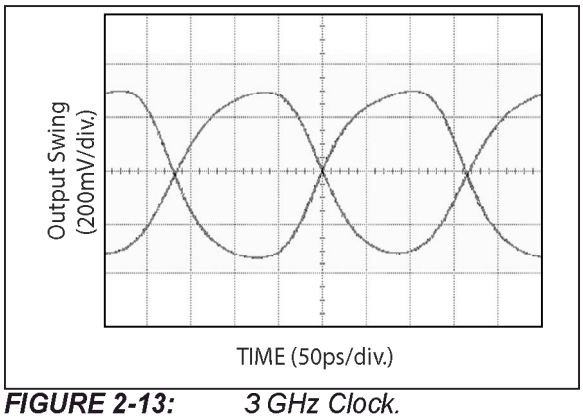


FIGURE 2-13: *3 GHz Clock.*

3.0 PHASE NOISE PLOTS

V_{CC} = +3.3V, T_A = +25°C.

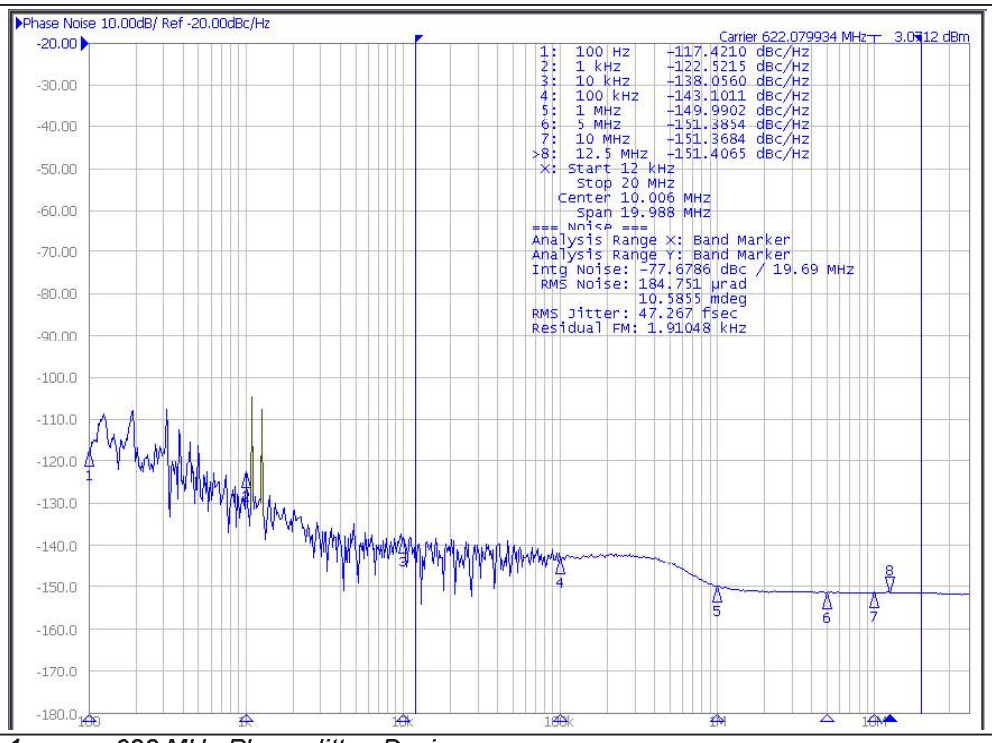


FIGURE 3-1: *622 MHz Phase Jitter, Device.*

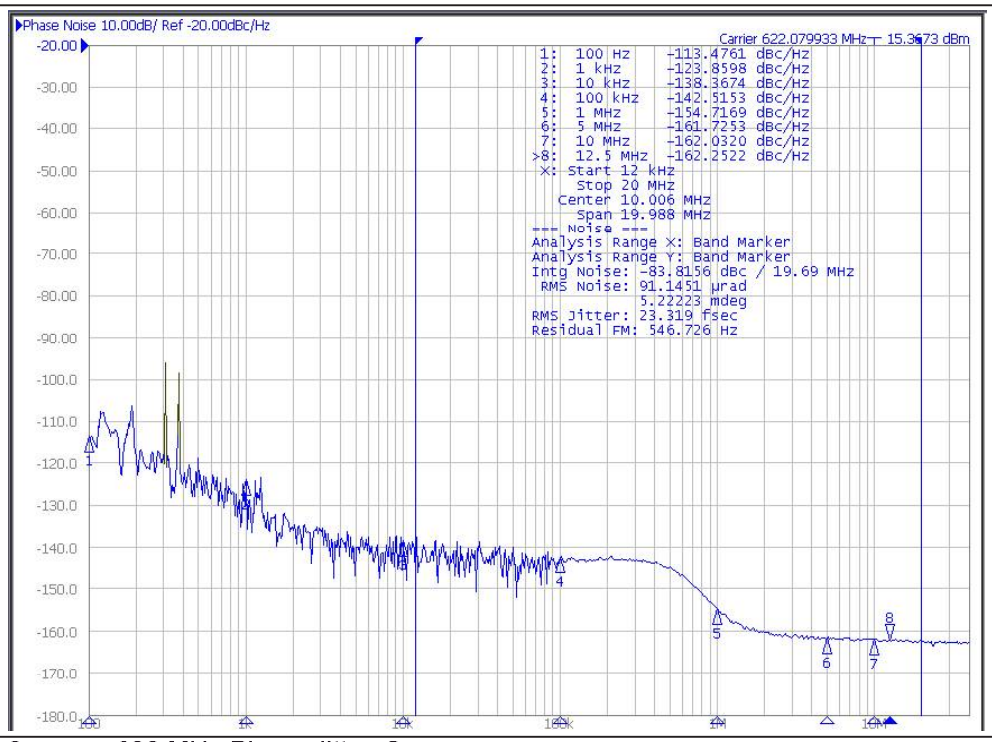


FIGURE 3-2: *622 MHz Phase Jitter, Source.*

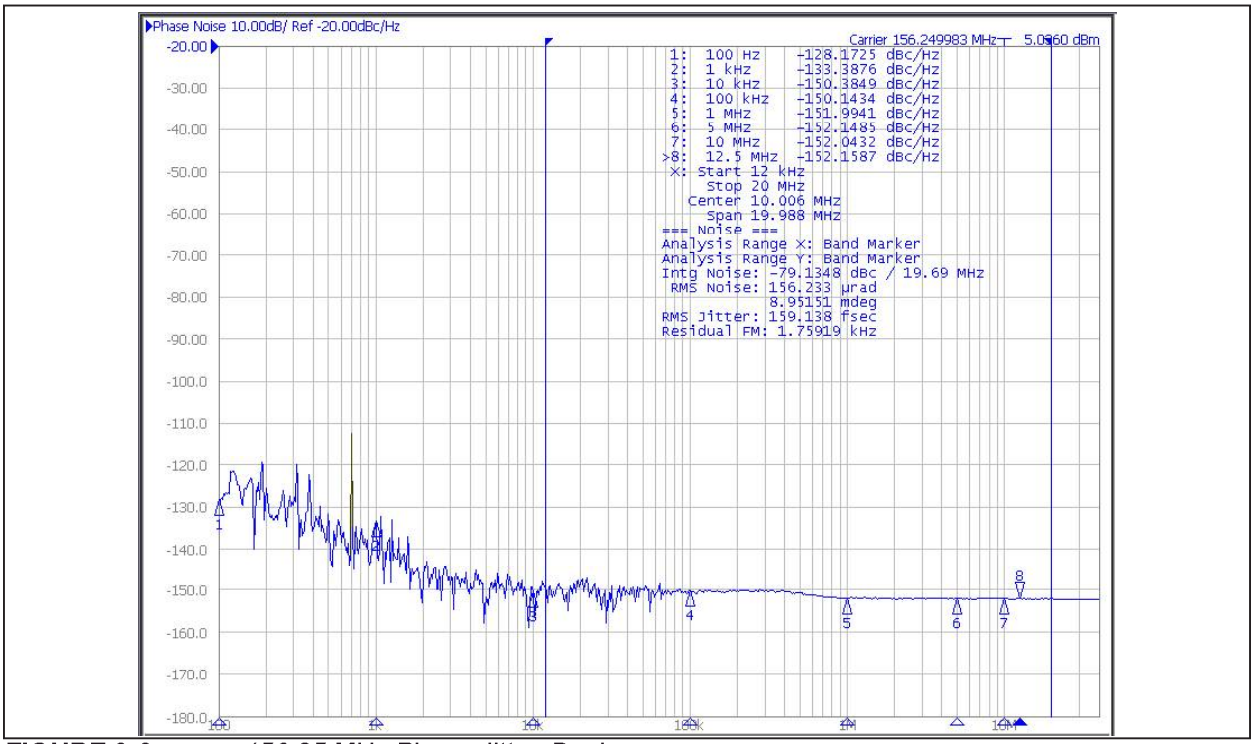


FIGURE 3-3: *156.25 MHz Phase Jitter, Device.*

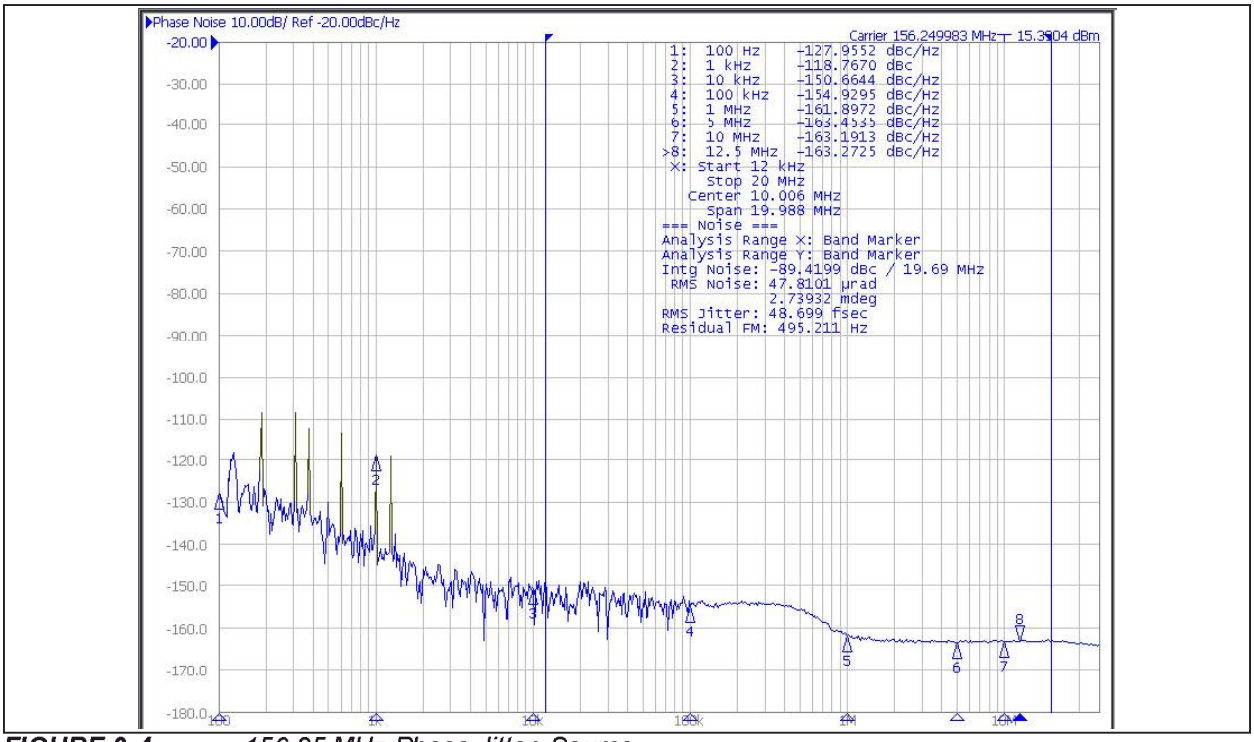


FIGURE 3-4: *156.25 MHz Phase Jitter, Source.*

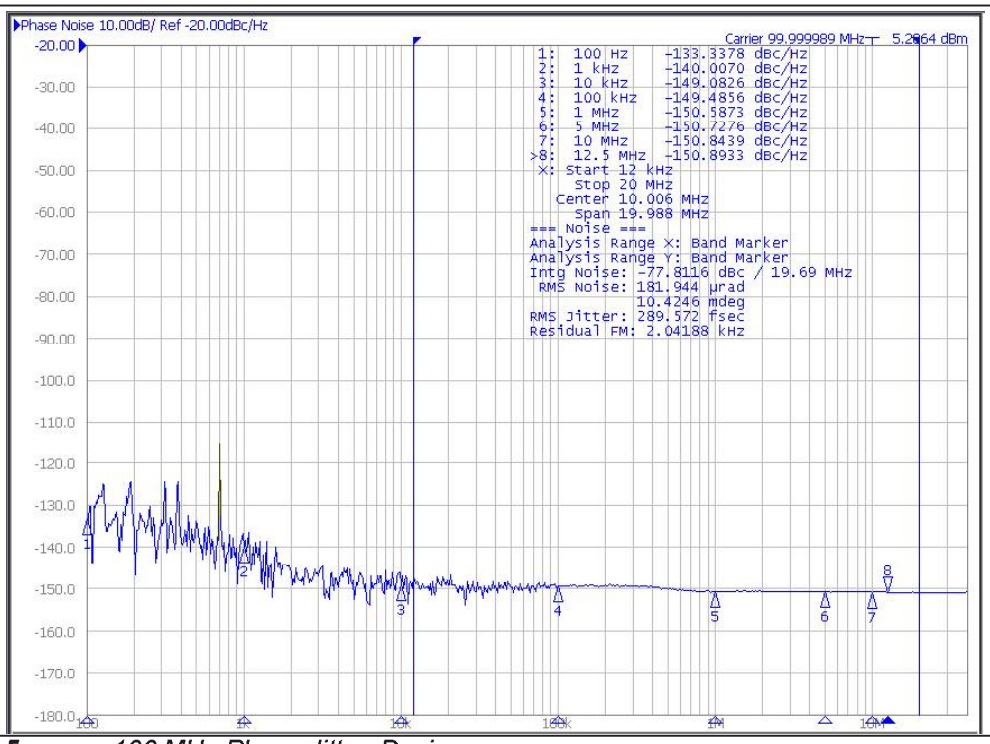


FIGURE 3-5: *100 MHz Phase Jitter, Device.*

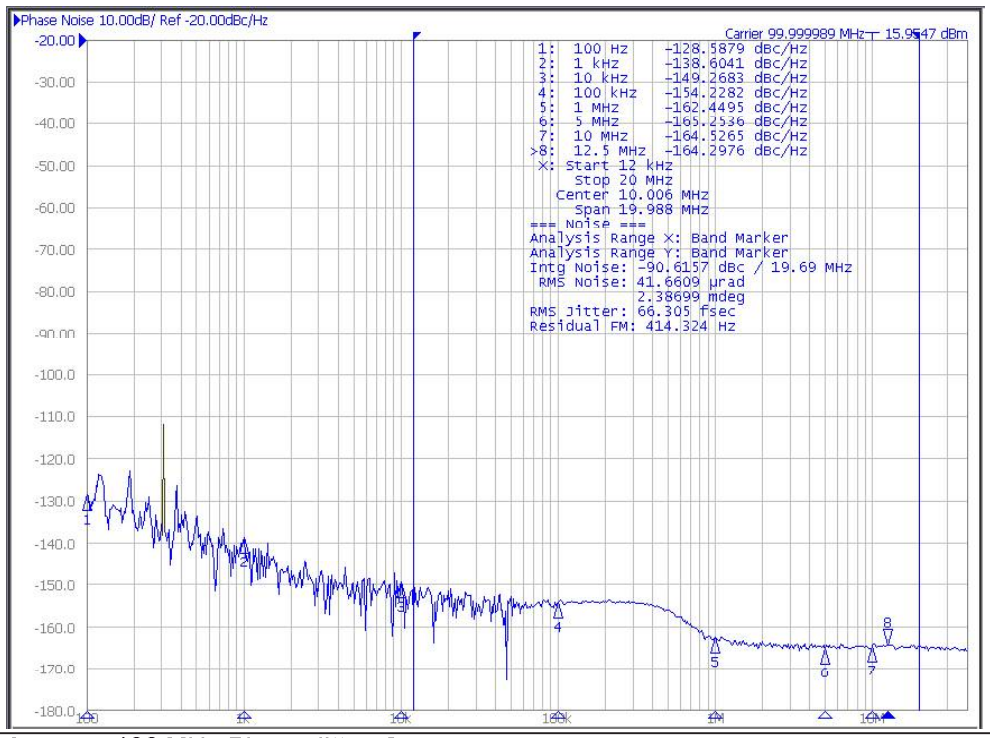


FIGURE 3-6: *100 MHz Phase Jitter, Source.*

4.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 4-1.

TABLE 4-1: PIN FUNCTION TABLE

Pin Number	Symbol	Description
1, 4	IN, /IN	Differential Input: This input pair is the differential signal input to the device. Input accepts DC-coupled differential signals as small as 100 mV (200 mV_{PP}). Each pin of this pair internally terminates with 50Ω to the VT pin. If the input swing falls below a certain threshold (typical 30 mV), the Fail Safe Input (FSI) feature will guarantee a stable output by latching the output to its last valid state. See the Input Interface Applications section.
2	VT	Input Termination Center Tap: Each side of the differential input pair terminates to the VT pin. This pin provides a center-tap to a termination network for maximum interface flexibility. See the Input Interface Applications section.
3	VREF-AC	Reference Voltage: This output biases to V_{CC} – 1.2V. It is used for AC-coupling inputs IN and /IN. Connect VREF-AC directly to the VT pin. Bypass with 0.01 µF low-ESR capacitor to VCC. Maximum sink/source current is ±1.5 mA. See the Input Interface Applications section.
5, 8,13, 16	VCC	Positive Power Supply: Bypass with 0.1 µF//0.01 µF low-ESR capacitors as close to the VCC pins as possible.
6, 7, 14, 15	GND, Exposed pad	Ground: Exposed pad must be connected to a ground plane that is the same potential as the ground pins.
9, 10 11, 12	/Q1, Q1 /Q0, Q0	LVPECL Differential Output Pairs: Differential buffered copies of the input signal. The output swing is typically 800 mV. Unused output pair may be left floating with no impact on jitter. See the LVPECL Output Termination section.

5.0 FUNCTIONAL DESCRIPTION

5.1 Fail-Safe Input (FSI)

The input includes a special fail-safe circuit to sense the amplitude of the input signal and to latch the outputs when there is no input signal present or when the amplitude of the input signal drops sufficiently below 100 mV_{PK} (200 mV_{PP}), typically 30 mV_{PK}. Maximum frequency of SY58607U is limited by the FSI function.

5.2 Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing, the FSI function will eliminate a metastable condition and guarantee a stable output. No ringing and no undetermined state will occur at the output under these conditions.

Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on rise and fall time of the input signal and on its amplitude. Refer to the Typical Performance Curves section for detailed information.

Timing Diagrams

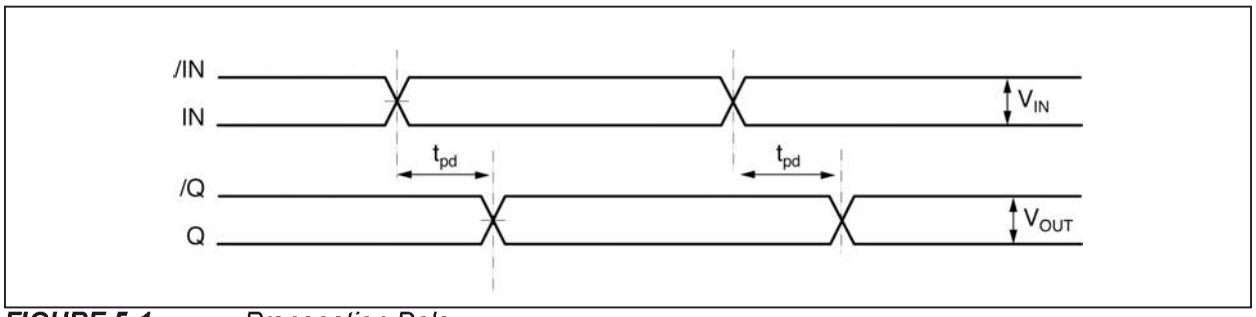


FIGURE 5-1: *Propagation Delay.*

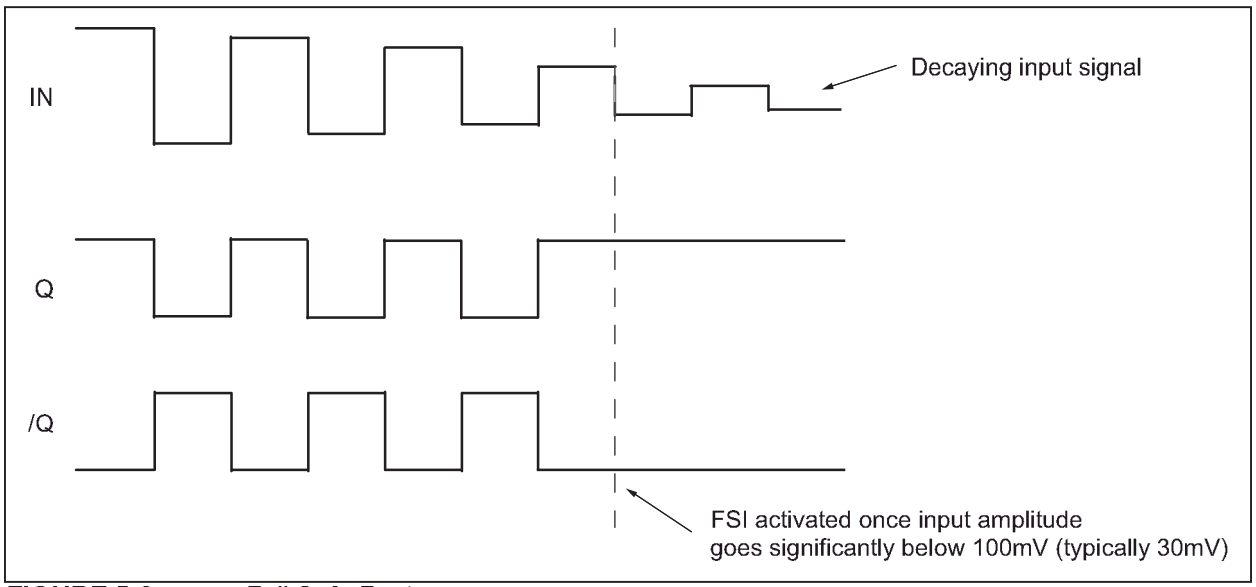


FIGURE 5-2: *Fail Safe Feature.*

Input and Output Stage

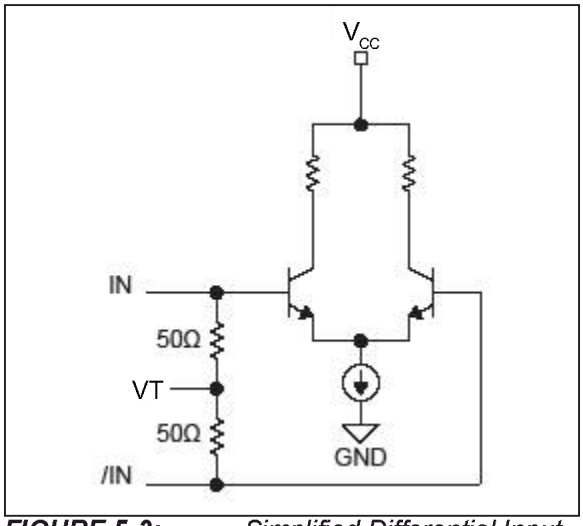


FIGURE 5-3: *Simplified Differential Input Buffer.*

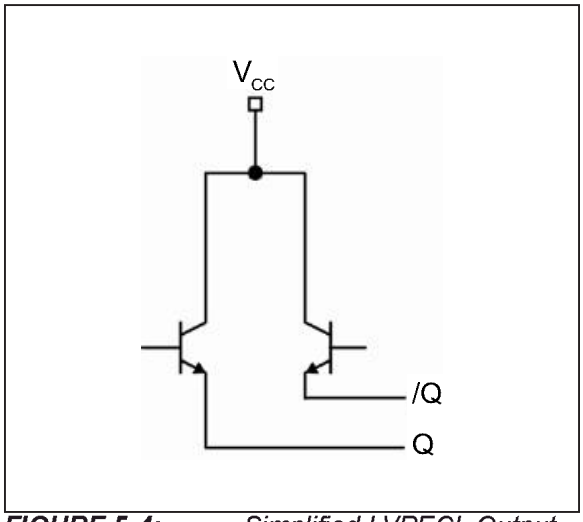


FIGURE 5-4: *Simplified LVPECL Output Buffer.*

Single-Ended and Differential Swings

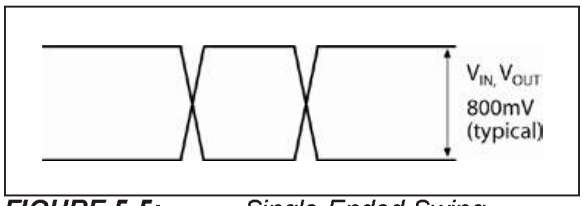


FIGURE 5-5: *Single-Ended Swing.*

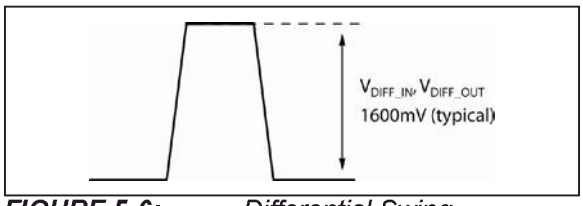


FIGURE 5-6: *Differential Swing.*

6.0 INPUT INTERFACE APPLICATIONS

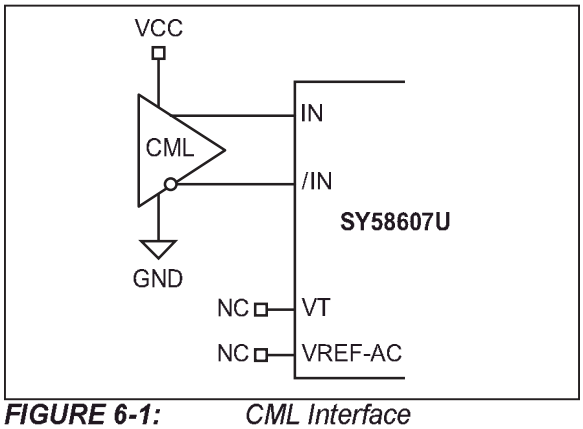


FIGURE 6-1: *CML Interface (DC-Coupled) May connect VT to VCC.*

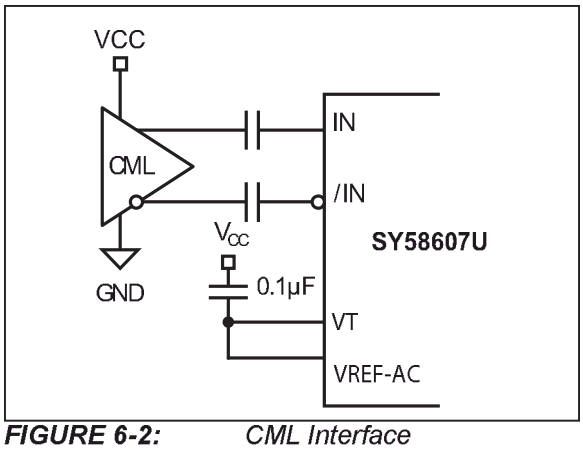


FIGURE 6-2: *CML Interface (AC-Coupled).*

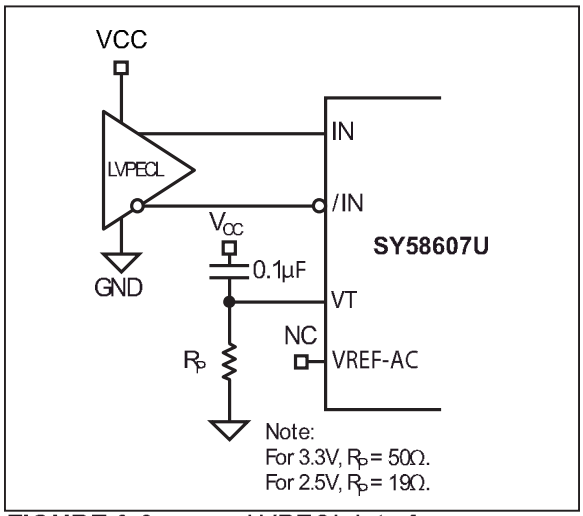


FIGURE 6-3: *LVPECL Interface (DC-Coupled).*

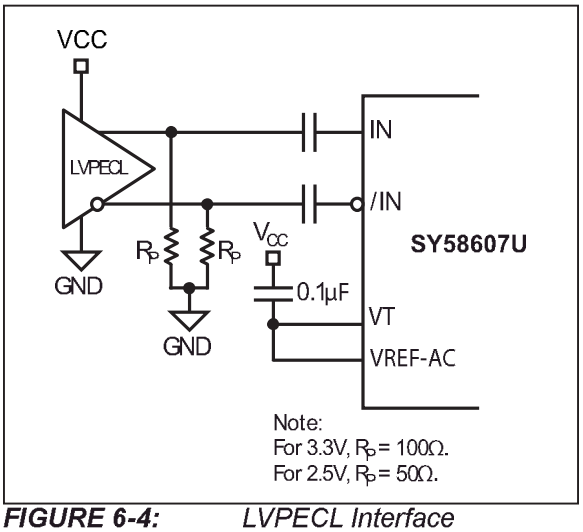


FIGURE 6-4: *LVPECL Interface (AC-Coupled).*

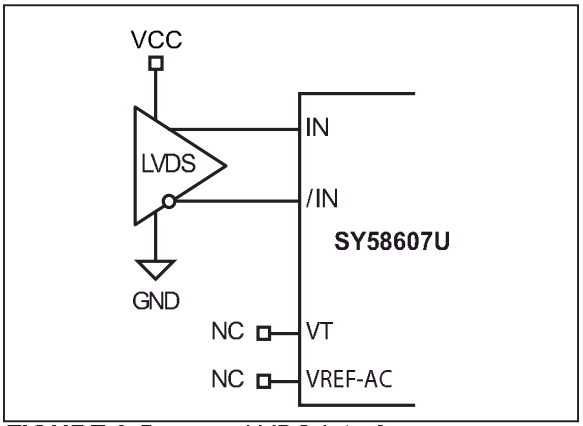


FIGURE 6-5: *LVDS Interface (DC-Coupled).*

7.0 LVPECL OUTPUT TERMINATION

LVPECL outputs have very low output impedance (open emitter), and small signal swing which results in low EMI. LVECL is ideal for driving 50Ω and 100Ω-controlled impedance transmission lines. There are several techniques in terminating the LVPECL output, as shown in Figure 7-1 and Figure 7-2.

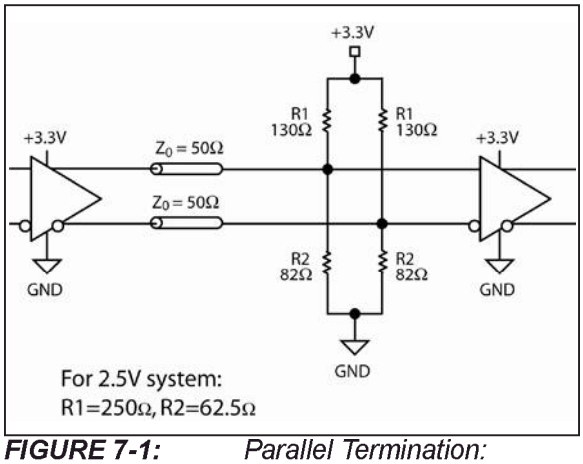


FIGURE 7-1: *Parallel Termination: Thevenin Equivalent.*

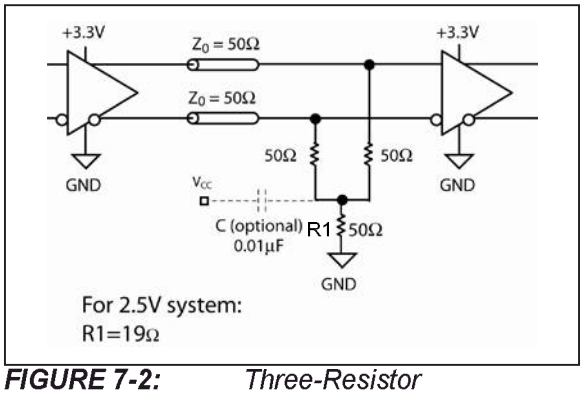


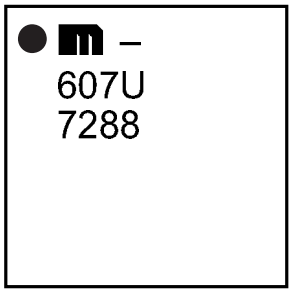
FIGURE 7-2: *Three-Resistor "Y-Termination".*

8.0 PACKAGING INFORMATION

8.1 Package Marking Information

16-Lead QFN*

Example

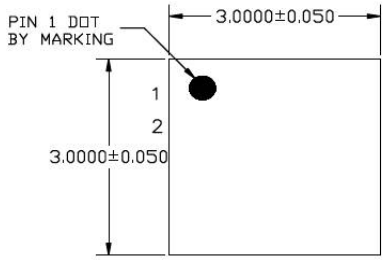


Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	●, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	
	Underbar (_) and/or Overbar (¯) symbol may not be to scale.	

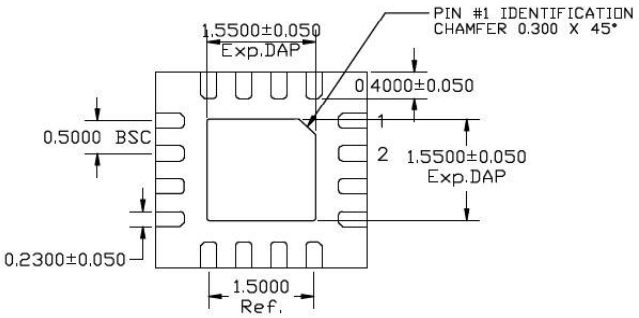
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

TITLE
16 LEAD QFN 3x3mm PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

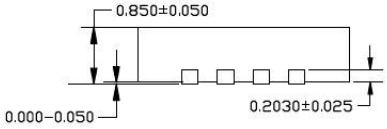
DRAWING #	QFN33-16LD-PL-1	UNIT	MM



TOP VIEW
NOTE: 1, 2, 3



BOTTOM VIEW
NOTE: 1, 2, 3

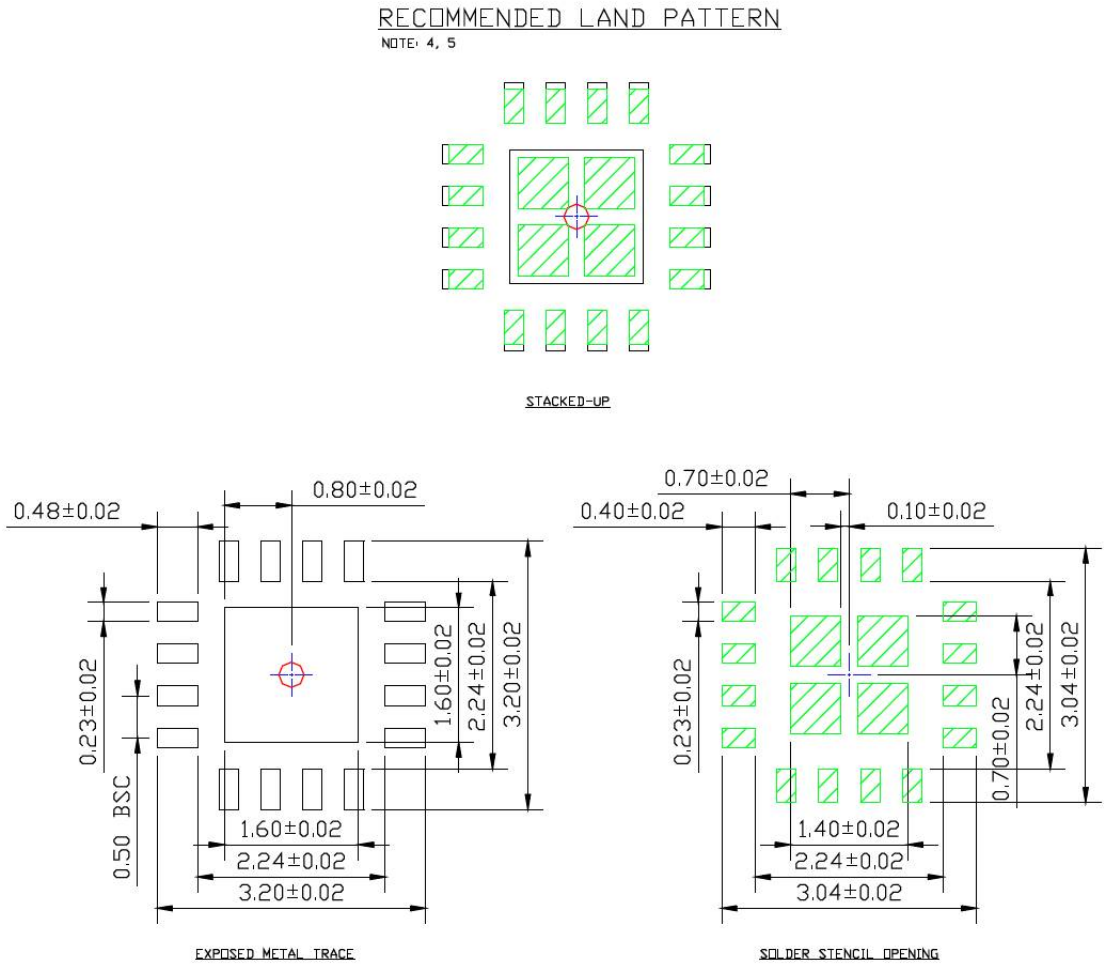


SIDE VIEW
NOTE: 1, 2, 3

NOTE:
1. MAX PACKAGE WARPAGE IS 0.05 MM
2. MAX ALLOWABLE BURR IS 0.076 MM IN ALL DIRECTIONS
3. PIN #1 IS ON TOP WILL BE LASER MARKED
4. RED CIRCLE IN LAND PATTERN INDICATE THERMAL VIA. SIZE SHOULD BE 0.30-0.35 MM IN DIAMETER AND SHOULD BE CONNECTED TO GND FOR MAX THERMAL PERFORMANCE
5. GREEN RECTANGLES (SHADED AREA) indicate SOLDER STENCIL OPENING ON EXPOSED PAD AREA. SIZE SHOULD BE 0.60x0.60 MM IN SIZE, 0.20 MM SPACING.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

POD-Land Pattern drawing # QFN33-16LD-PL-1



APPENDIX A: REVISION HISTORY

Revision A (July 2019)

- Converted Micrel document SY58607U to Microchip data sheet template DS20006227A.
- Minor text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	X	X	X	XX
Device	Supply Voltage	Package	Temperature Range	Tape and Reel

Device:	SY58607:	3.2 Gbps Precision, 1:2 LVPECL Fanout Buffer with Internal Termination and Fail Safe Input	
Supply Voltage:	U	=	2.5V/3.3V
Package:	M	=	3 mm x 3 mm QFN-16
Temperature Range:	G	=	–40°C to 85°C (NiPdAu Lead-Free)
Special Processing:	<blank>	=	100/Tube
	TR	=	1,000/Reel

Examples:

a) SY58607UMG: SY58607, 2.5V/3.3V Supply Voltage, 3 mm x 3 mm 16-Lead QFN, –40°C to +85°C Temperature Range, 100/Tube

b) SY58607UMG-TR: SY58607, 2.5V/3.3V Supply Voltage, 3 mm x 3 mm 16-Lead QFN, –40°C to +85°C Temperature Range, 1,000/Reel

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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